



*Advanced Chip Optical I/O Interconnects
for Next Generation connectivity*

ICON Photonics overview



Technological Company created in 2018



Offices and Clean Room Facilities in France, Paris region



Spinoff of CNRS research center

- **10+ years of R&D** in microfabrication and photonics packaging
- 650m² cleanrooms **production-line** (Class 10) platform
- **Licensing agreement** worldwide with exclusivity **including 6 granted patents**



i-Lab ICON Photonics is **Grand Prize winner** of the i-Lab innovation competition

Know-how on Semiconductor
Manufacturing processes

Expertise in Microwave &
Photonics

The next generation Chip Optical I/O Interconnects

Our Multidisciplinary Team

Business and Management



Charles GOËLLER, Eng
COO, Partner

5 years of experience in international business development of technological solutions.



Carlos VIANA, PhD
CEO & co-founder

12 years of experience in photonics technologies, Administration & Business development.



Jean-Luc POLLEUX, PhD
CSO & co-founder

Professor at ESIEE Paris, 20 years of experience in Photonics and microwaves.



Operations



Aziz, Eng
Business Developer
Engineer



Mayte, PhD
Photonics
Engineer



Ronghua, PhD (C)
Photonics R&D
Engineer



Benjamin, PhD
Microfabrication
Engineer



Mathieu, Eng
Process Quality
Engineer



Advisory Board



Michel MARITON

Doctor in Physics, 30 years of professional experience in Photonics industry. Former CEO of HORIBA Jobin Yvon, SURYS and Executive Manager at AMPLITUDE Laser.



Dominique DUFOR

Graduated in Chemistry, MBA ICG Lyon, over 30 years' experience in senior executive management in worldwide companies (J&J, Bayer Pharma, Nutricia Danone, DELL, Carestream Dental and Danaher Group).

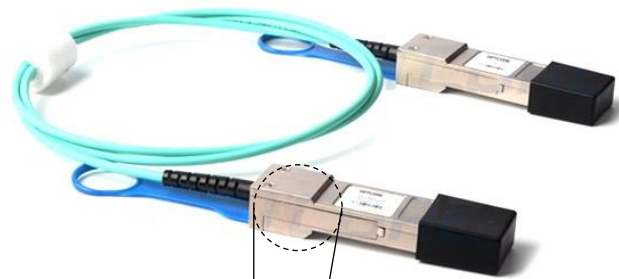


Andreas UMBACH

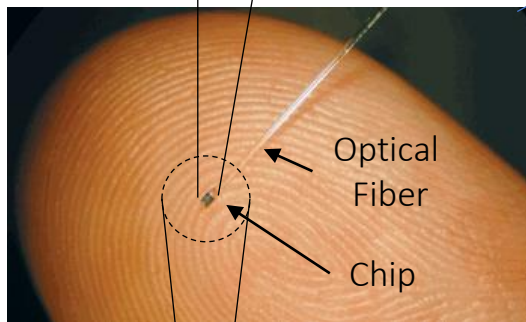
Doctor in Physics, Andreas has more than 20 years experience in Photonics industry. CEO at Aucept, former CEO at u²t Photonics and General Manager at Finisar Germany GmbH

Chip Optical I/O interconnects needs

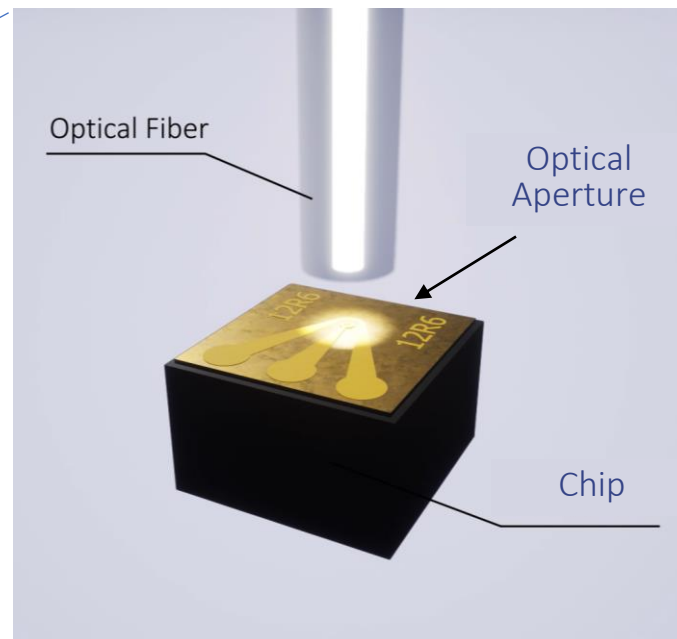
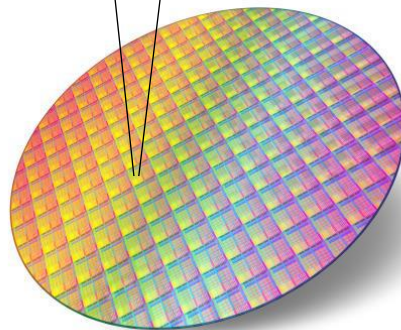
Optical Cable



Chip Optical I/O interconnects



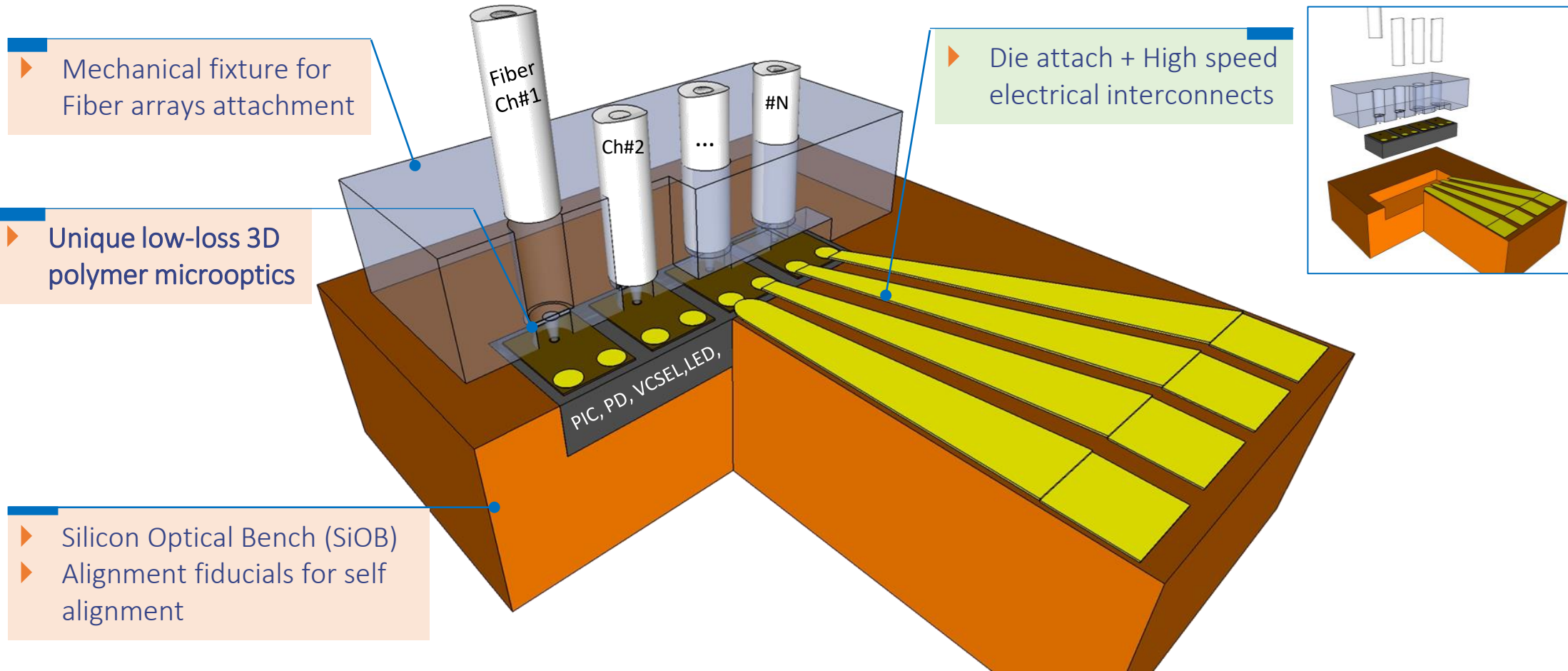
Chip Maker
Wafer: ~100k chips



I/O interconnects: losses, bandwidth, integration, packaging

Market needs: Miniaturization – Reliability – Scalability and Cost – Versatility

Wafer-Level integration platform: Optical Micro-Bench



Photonics + optics + Electronics integration using Semiconductor manufacturing Process

Dynamic market & opportunities



Strategic targeted market
with strong added value



Consistent growth



USA, Asia, Europe

Optical Transceivers



2026: \$20B ↗ **12.5%**
(\$150M – SOM)

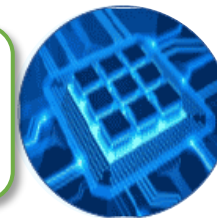
Quantum Computing



2026: \$1.2B ↗ **13%**
(\$10M – SOM)

Emergent market opportunities

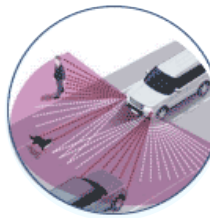
- Co-packaged optics / 3D Sensing / Lidar



TAM@2030: \$ 2.3B

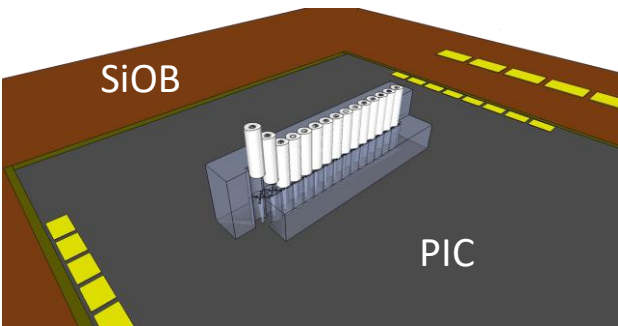


\$ 26B



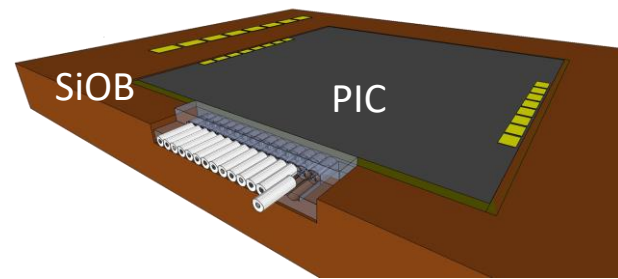
\$ 12B

Product roadmap Roadmap driven by Customer Engagement



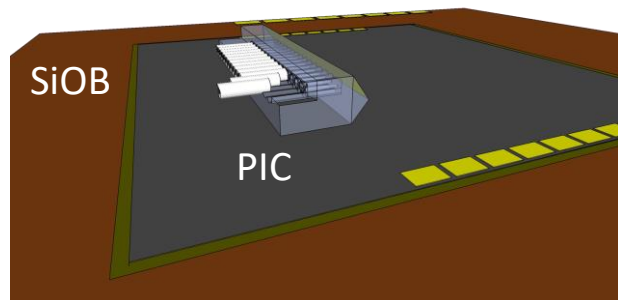
P1: Top I/O array interconnects

Customer type: Optical module makers



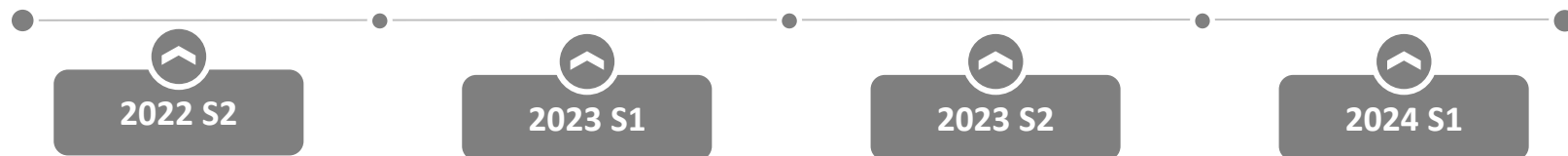
P2: Edge I/O array interconnects

Customer type: Optical module makers



P3: 90deg I/O array interconnects

Customer type: Optical module makers



Investment allocation

2018-2021 non-equity investment:
1M€

2.5M€
Seed fund

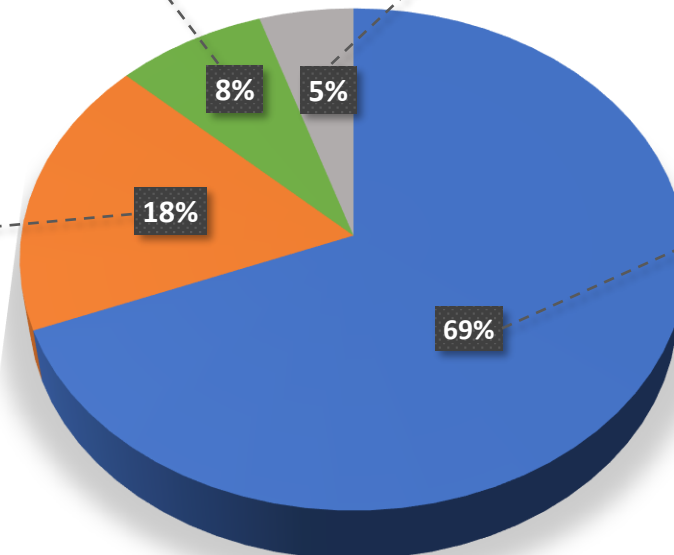
Series A in 2025 for production growth:
7M€

Patent portfolio & IP protection
› Innovation strategy

Other OPEX

Marketing and Communication

- › Branding
- › Sales staff
- › Industrial Exhibition USA, Asia , EU



Go-to-market

- › Product development
- › Manufacturing capabilities & Operations
- › Engineering staff



Merci

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www.icon-photonics.com

